

BT134-500/600/800

Rev.E Mar.-2016

描述 / Descriptions

TO-126 塑封封装 双向可控硅。 Triac in a TO-126 Plastic Package.

特征 / Features

高双向瞬态电压能力和高热循环性能。

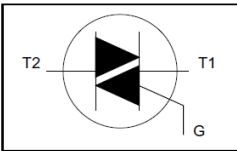
high bidirectional transient and blocking voltage capability and high thermal cycling performance.

用途 / Applications

主要用于马达控制，工业和家庭照明灯，加热控制和静电开关。

Typical applications include motor control, industrial and domestic lighting, heating and static switching.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : main terminal 1

PIN 2 : main terminal 2

PIN 3 : Gate

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。 See Marking Instructions.

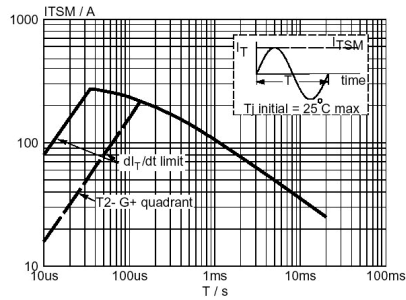
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Repetitive peak off-state voltages	V_{DRM}	500 600 800	V
RMS on-state current	$I_{T(RMS)}$	4.0	A
Non-repetitive peak on-state current	$I_{TSM}(t=20ms)$	25	A
Non-repetitive peak on-state current	$I_{TSM}(t=16.7ms)$	27	A
I^2t for fusing	$I^2t_{(t=10ms)}$	3.1	A ² S
Repetitive rate of rise of on-state current after triggering	$di_T/dt_{(T2+G+)}$	50	A/μS
Peak gate current	I_{GM}	2.0	A
Peak gate voltages	V_{GM}	5.0	V
Peak gate power	P_{GM}	5.0	W
Average gate power	$P_{G(AV)}$	0.5	W
Junction Temperature	T_j	125	°C
Storage Temperature Range	T_{stg}	-40~150	°C

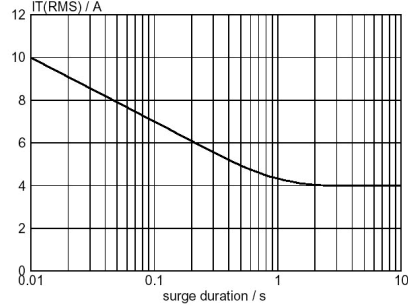
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ		最大值 Max				单位 Unit
				F/G	E	E	F	G		
Gate trigger current	I_{GT}	BT134-		F/G	E		E	F	G	mA
		$V_D=12V$ $I_T=0.1A$	T2+G+	5.0	2.5	35	10	25	50	
			T2+G-	8.0	4.0	35	10	25	50	
			T2-G-	11	5.0	35	10	25	50	
Latching current	I_L	$V_D=12V$ $I_{GT}=0.1A$	T2-G+	30	11	70	25	70	100	mA
			T2+G+	7.0	3.0	20	15	20	20	
			T2+G-	16	10	30	20	30	45	
			T2-G-	5.0	2.5	20	15	20	30	
Holding current	I_H	$V_D=12V$ $I_{GT}=0.1A$		5.0	2.2	15	15	15	30	mA
On-state voltage	V_T	$I_T=5.0A$		1.4		1.7				V
Gate trigger voltage	V_{GT}	$V_D=12V$ $I_T=0.1A$		0.7		1.5				V
		$V_D=400V, I_T=0.1A,$ $T_j=125^\circ C$	0.25	0.4						
Off-state leakage current	I_D	$V_D=V_{DRM(max)}$ $T_j=125^\circ C$		0.1		0.5				mA
Critical rate of rise of off-state current	t_{gt}	$I_{TM}=6A, V_D=V_{DRM}$ $I_G=0.1A$ $di_g/dt=5A/\mu s$		2.0						μs
Repetitive peak off-state current	dV_D/dt	$V_D=67\% V_{DRM}$ gate open $T_j=125^\circ C$		250						V/μs

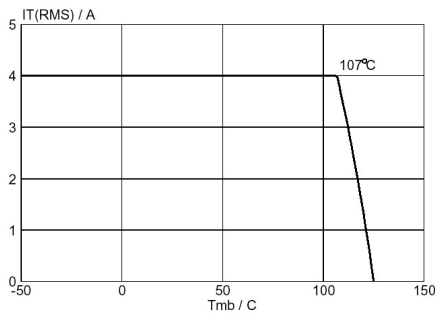
电参数曲线图 / Electrical Characteristic Curve



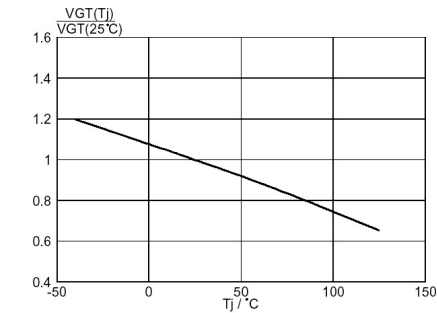
Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20ms$.



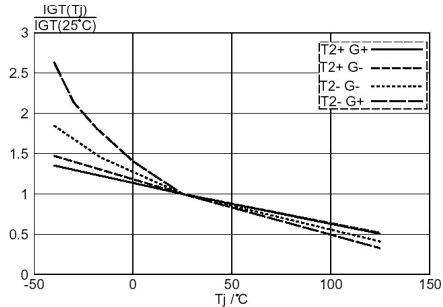
Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50 Hz$; $T_{mb} \leq 107^\circ C$.



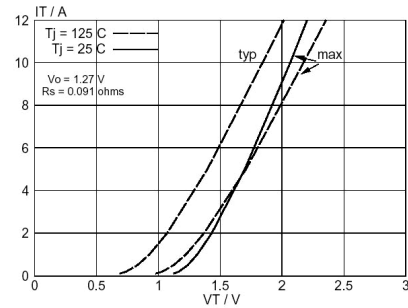
Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .



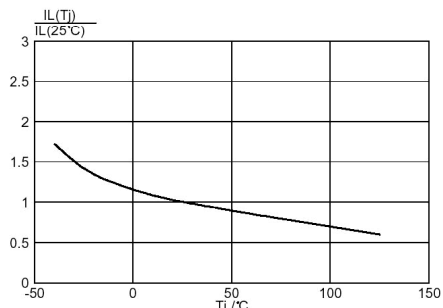
Normalised gate trigger voltage $V_{GT}(T_j) / V_{GT}(25^\circ C)$, versus junction temperature T_j .



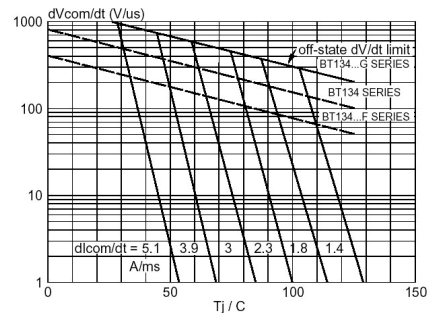
Normalised gate trigger current $I_{GT}(T_j) / I_{GT}(25^\circ C)$, versus junction temperature T_j .



Typical and maximum on-state characteristic.



Normalised latching current $I_L(T_j) / I_L(25^\circ C)$, versus junction temperature T_j .

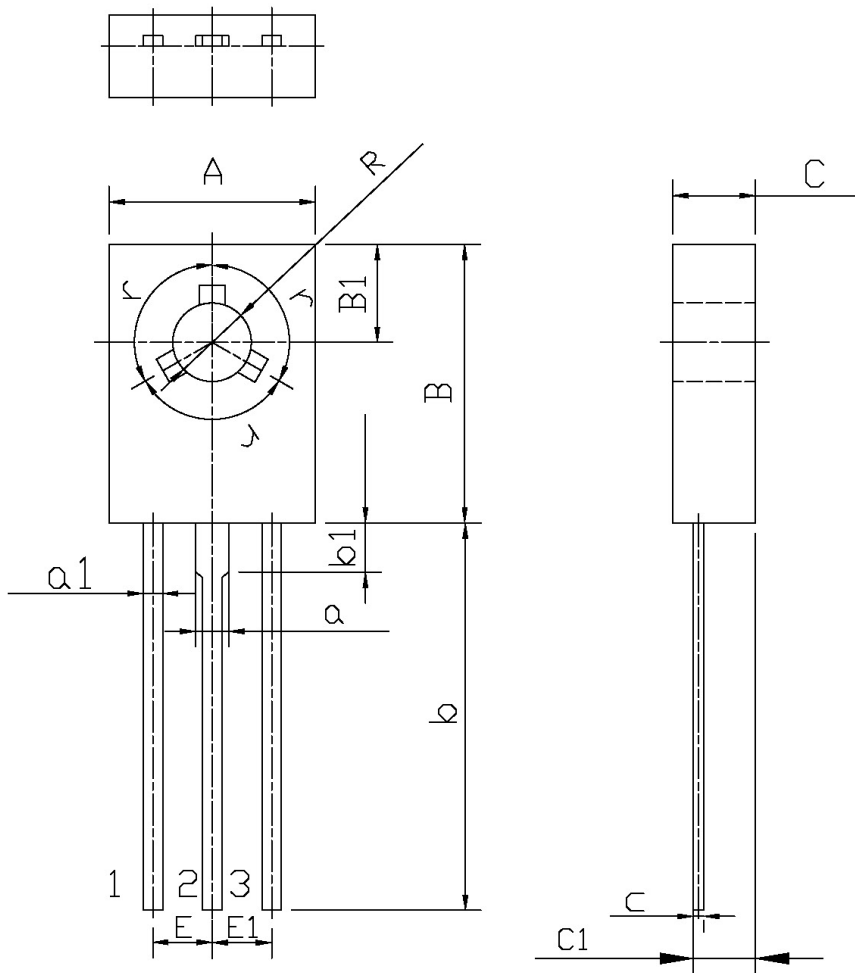


Typical commutation dV/dt versus junction temperature, parameter commutation dl_T/dt . The triac should commute when the dV/dt is below the value on the appropriate curve for pre-commutation dl_T/dt .

外形尺寸图 / Package Dimensions

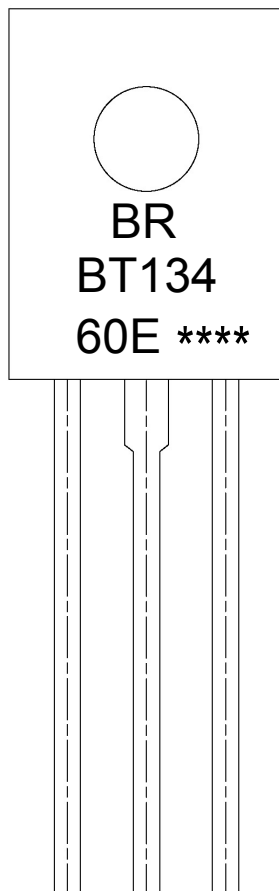
T0-126

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	7.8	8.2	a1	0.66	0.86
B	10.6	11.0	E	2.1	2.5
B1	3.6	4.0	C	2.7	2.9
R	2.9	3.3	C1	1.57	1.77
b	14	16	c	0.3	0.6
b1	1.9		a	1.37	
E1	2.1	2.5	r	120°	

印章说明 / Marking Instructions



说明：

BR： 为公司代码

BT134： 为型号代码

60E： 为 V_{RRM} 、 I_{GT} 分档代码

****： 为生产批号代码，随生产批号变化。

Note:

BR: Company Code

BT134: Product Type.

60E: V_{RRM} 、 I_{GT} Bracket code

****: Lot No. Code, code change with Lot No.

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-126/F	500	6	3,000	5	15,000	135×190	237×172×102	560×245×195

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-126/F	65	26	1,690	5	8,450	532×31×5.6	555×164×50	575×290×180

使用说明 / Notices